

DRAM

64 K x 16 DRAM

EDO PAGE MODE

FEATURES

- X16 organization
- EDO (Extended Data-Output) access mode
- 2 $\overline{\text{CAS}}$ Byte/Word Read/Write operation
- Single 5V ($\pm 10\%$) power supply
- TTL-compatible inputs and outputs
- 256-cycle refresh in 4ms
- Refresh modes : $\overline{\text{RAS}}$ only, $\overline{\text{CAS}}$ BEFORE $\overline{\text{RAS}}$ (CBR) and HIDDEN
- JEDEC standard pinout
- Key AC Parameter

	t _{RAC}	t _{CAC}	t _{RC}	t _{PC}
-25	25	8	43	10
-30	30	9	55	12
-35	35	10	65	14
-40	40	11	75	16

ORDERING INFORMATION - PACKAGE

40-pin 400mil SOJ

44 / 40-pin 400mil TSOP (TypeII)

PRODUCT NO.	PACKING TYPE
M11B11664A-25J	SOJ
M11B11664A-30J	
M11B11664A-35J	
M11B11664A-40J	
M11B11664A-25T	TSOPII
M11B11664A-30T	
M11B11664A-35T	
M11B11664A-40T	

GENERAL DESCRIPTION

The M11B11664A is a randomly accessed solid state memory, organized as 65,536 x 16 bits device. It offers Extended Data-Output , 5V($\pm 10\%$) single power supply. Access time (-25,-30,-35,-40) and package type (SOJ, TSOP II) are optional features of this family. All these family have $\overline{\text{CAS}}$ - before - $\overline{\text{RAS}}$, $\overline{\text{RAS}}$ -only refresh and Hidden refresh capabilities.

Two access modes are supported by this device : Byte access and Word access. Use only one of the two $\overline{\text{CAS}}$ and leave the other staying high will result in a BYTE access. WORD access happens when two $\overline{\text{CAS}}$ ($\overline{\text{CASL}}$, $\overline{\text{CASH}}$) are used. $\overline{\text{CASL}}$ transiting low during READ or WRITE cycle will output or input data into the lower byte (IO0~IO7), and $\overline{\text{CASH}}$ transiting low will output or input data into the upper byte (IO8~15).

PIN ASSIGNMENT

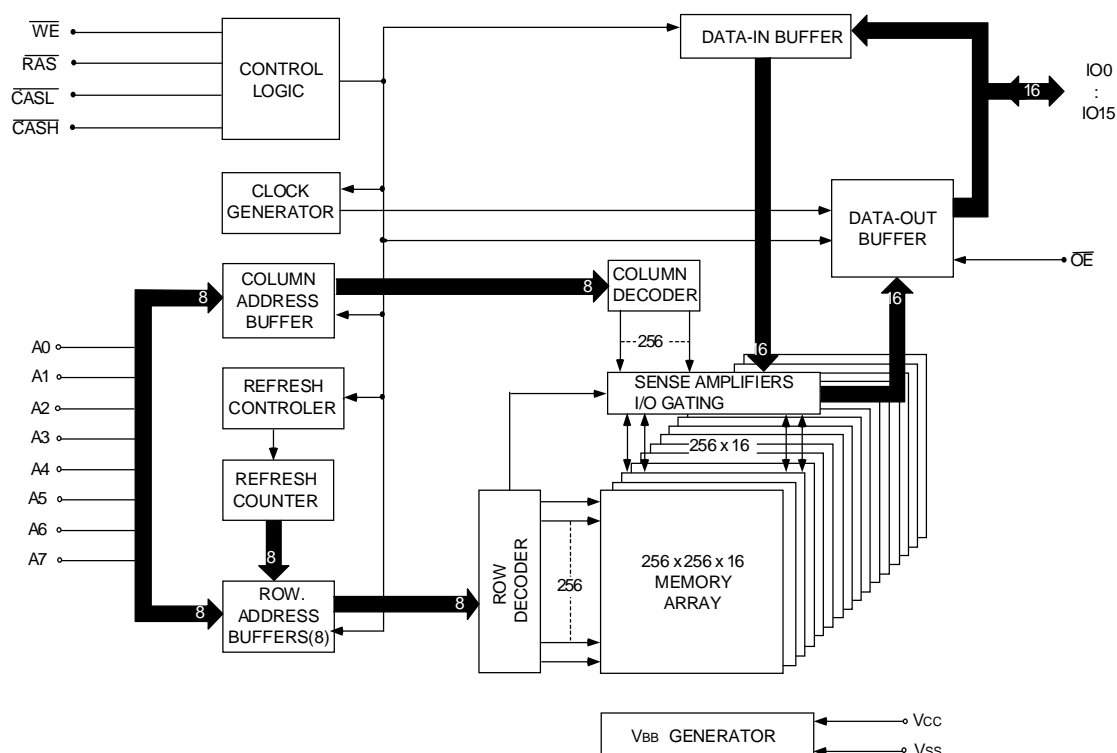
SOJ Top View

Vcc	1	40	Vss
I/O0	2	39	I/O15
I/O1	3	38	I/O14
I/O2	4	37	I/O13
I/O3	5	36	I/O12
Vcc	6	35	Vss
I/O4	7	34	I/O11
I/O5	8	33	I/O10
I/O6	9	32	I/O9
I/O7	10	31	I/O8
NC	11	30	NC
NC	12	29	$\overline{\text{CASL}}$
$\overline{\text{WE}}$	13	28	$\overline{\text{CASH}}$
$\overline{\text{RAS}}$	14	27	$\overline{\text{OE}}$
NC	15	26	NC
A0	16	25	A7
A1	17	24	A6
A2	18	23	A5
A3	19	22	A4
Vcc	20	21	Vss

TSOP (TypeII) Top View

Vcc	1	40	Vss
I/O0	2	39	I/O15
I/O1	3	38	I/O14
I/O2	4	37	I/O13
I/O3	5	36	I/O12
Vcc	6	35	Vss
I/O4	7	34	I/O11
I/O5	8	33	I/O10
I/O6	9	32	I/O9
I/O7	10	31	I/O8
NC	11	30	NC
NC	12	29	$\overline{\text{CASL}}$
$\overline{\text{WE}}$	13	28	$\overline{\text{CASH}}$
$\overline{\text{RAS}}$	14	27	$\overline{\text{OE}}$
NC	15	26	NC
A0	16	25	A7
A1	17	24	A6
A2	18	23	A5
A3	19	22	A4
Vcc	20	21	Vss

FUNCTIONAL BLOCK DIAGRAM



PIN DESCRIPTIONS

PIN NO.	PIN NAME	TYPE	DESCRIPTION
16~19,22~25	A0~A7	Input	Address Input Row Address : A0~A7 Column Address : A0~A7
14	\overline{RAS}	Input	Row Address Strobe
28	\overline{CASH}	Input	Column Address Strobe / Upper Byte Control
29	\overline{CASL}	Input	Column Address Strobe / Lower Byte Control
13	\overline{WE}	Input	Write Enable
27	\overline{OE}	Input	Output Enable
2~5,7~10,31~34,36~39	I/O0 ~ I/O15	Input / Output	Data Input / Output
1,6,20	V _{CC}	Supply	Power, 5V
21,35,40	V _{SS}	Ground	Ground
11,12,15,30	NC	-	No Connect

ABSOLUTE MAXIMUM RATINGS

Voltage on Any pin Relative to Vss ... -1V to +7V
 Operating Temperature, T_A (ambient)0 °C to +70 °C
 Storage Temperature (plastic)-55 °C to +150 °C
 Power Dissipation1.0W
 Short Circuit Output Current50mA

Permanent device damage may occur if "Absolute Maximum Ratings" are exceeded. This is a stress rating only, and functional operation of the device above those conditions indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC ELECTRICAL CHARACTERISTICS AND RECOMMENDED

OPERATING CONDITIONS (0 °C ≤ T_A ≤ 70 °C ; V_{CC} = 5V ± 10% unless otherwise noted)

PARAMETER	CONDITIONS	SYMBOL	MIN	MAX	UNITS	NOTES
Supply Voltage		V _{CC}	4.5	5.5	V	1
Supply Voltage		V _{SS}	0	0	V	
Input High Voltage		V _{IH}	2.4	V _{CC} +1	V	1
Input Low Voltage		V _{IL}	-1.0	0.8	V	1
Input Leakage Current	0V ≤ V _{IH} ≤ 7V	I _{LI}	-10	10	μA	
Output Leakage Current	0V ≤ V _{OUT} ≤ 7V Output(s) disable	I _{LO}	-10	10	μA	
Output High Voltage	I _{OH} = -5 mA	V _{OH}	2.4	-	V	
Output Low Voltage	I _{OL} = 4.2 mA	V _{OL}	-	0.4	V	

Note : 1.All Voltages referenced to Vss

PARAMETER	CONDITIONS	SYMBOL	MAX				UNITS	NOTES
			-25	-30	-35	-40		
Operating Current	$\overline{\text{RAS}}$, $\overline{\text{CAS}}$ cycling , t _{RC} =min	I _{CC1}	170	150	130	120	mA	1,2
Standby Current	TTL interface , $\overline{\text{RAS}}$, $\overline{\text{CAS}}$ = V _{IH} , D _{OUT} =High-Z	I _{CC2}	4	4	4	4	mA	
	CMOS interface, $\overline{\text{RAS}}$, $\overline{\text{CAS}}$ ≥ V _{CC} -0.2V		2	2	2	2	mA	
RAS only refresh Current	t _{RC} = min	I _{CC3}	170	150	130	120	mA	2
EDO Page Mode Current	t _{PC} = min	I _{CC4}	170	150	130	120	mA	1,3
Standby Current	$\overline{\text{RAS}}$ =V _{IH} , $\overline{\text{CAS}}$ = V _{IL}	I _{CC5}	5	5	5	5	mA	1
$\overline{\text{CAS}}$ Before $\overline{\text{RAS}}$ Refresh Current	t _{RC} = min	I _{CC6}	170	150	130	120	mA	

Note : 1. ICC max is specified at the output open condition.

2. Address can be changed twice or less while $\overline{\text{RAS}}$ =V_{IL} .

3. Address can be changed once or less while $\overline{\text{CAS}}$ =V_{IH} .

CAPACITANCE ($T_a = 25^\circ\text{C}$, $V_{CC} = 5V \pm 10\%$)

PARAMETER	SYMBOL	TYP	MAX	UNIT
Input Capacitance (address)	C_{i1}	-	5	pF
Input Capacitance ($\overline{\text{RAS}}$, $\overline{\text{CASH}}$, $\overline{\text{CASL}}$, $\overline{\text{WE}}$, $\overline{\text{OE}}$)	C_{i2}	-	7	pF
Output capacitance (I/O0~I/O15)	$C_{i/o}$	-	10	pF

AC ELECTRICAL CHARACTERISTICS ($T_a = 0$ to 70°C , $V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V$) (note 14)

Test Conditions

Input timing reference levels : 0V, 3V

Output reference level : $V_{OL} = 0.8V$, $V_{OH} = 2.0V$

Output Load : 2TTL gate + CL (50pF)

Assumed $t_r = 2ns$

PARAMETER	SYMBOL	-25		-30		-35		-40		UNIT	Notes
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
Read or Write Cycle Time	t_{RC}	43		55		65		75		ns	
Read Write Cycle Time	t_{RWC}	65		85		95		105		ns	
EDO-Page-Mode Read or Write Cycle Time	t_{PC}	10		12		14		16		ns	22
EDO-Page-Mode Read-Write Cycle Time	t_{PCM}	32		37		42		47		ns	22
Access Time From $\overline{\text{RAS}}$	t_{RAC}		25		30		35		40	ns	4
Access Time From $\overline{\text{CAS}}$	t_{CAC}		8		9		10		11	ns	5,20
Access Time From $\overline{\text{OE}}$	t_{OAC}		8		9		10		11	ns	13,20
Access Time From Column Address	t_{AA}		12		15		18		20	ns	
Access Time From $\overline{\text{CAS}}$ Precharge	t_{ACP}		14		17		20		22	ns	20
$\overline{\text{RAS}}$ Pulse Width	t_{RAS}	25	10,000	30	10,000	35	10,000	40	10,000	ns	
$\overline{\text{RAS}}$ Pulse Width (EDO Page Mode)	t_{RASC}	25	100,000	30	100,000	35	100,000	40	100,000	ns	
$\overline{\text{RAS}}$ Hold Time	t_{RSH}	8		9		10		11		ns	25
$\overline{\text{RAS}}$ Precharge Time	t_{RP}	15		20		25		30		ns	
$\overline{\text{CAS}}$ Pulse Width	t_{CAS}	4	10,000	5	10,000	5	10,000	6	10,000	ns	24
$\overline{\text{CAS}}$ Hold Time	t_{CSH}	21		26		30		35		ns	19
$\overline{\text{CAS}}$ Precharge Time	t_{CP}	4		4		5		5		ns	6,23
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ Delay Time	t_{RCD}	10	17	10	21	10	25	10	29	ns	7,18
$\overline{\text{CAS}}$ to $\overline{\text{RAS}}$ Precharge Time	t_{CRP}	5		5		5		5		ns	19
Row Address Setup Time	t_{ASR}	0		0		0		0		ns	
Row Address Hold Time	t_{RAH}	5		5		5		5		ns	
$\overline{\text{RAS}}$ to Column Address Delay Time	t_{RAD}	8	13	8	15	8	17	8	20	ns	8
Column Address Setup Time	t_{ASC}	0		0		0		0		ns	18
Column Address Hold Time	t_{CAH}	5		5		5		5		ns	18
Column Address Hold Time (Reference to $\overline{\text{RAS}}$)	t_{AR}	22		26		30		34		ns	
Column Address to $\overline{\text{RAS}}$ Lead Time	t_{RAL}	12		15		18		20		ns	

(Continued)

PARAMETER	SYMBOL	-25		-30		-35		-40		UNIT	Notes
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
Read Command Setup Time	t _{RCS}	0		0		0		0		ns	15,18
Read Command Hold Time Reference to $\overline{\text{CAS}}$	t _{RCH}	0		0		0		0		ns	9,15,19
Read Command Hold Time Reference to $\overline{\text{RAS}}$	t _{RRH}	0		0		0		0		ns	9
$\overline{\text{CAS}}$ to Output in Low-Z	t _{CLZ}	3		3		3		3		ns	20
Output Buffer Turn-off Delay From $\overline{\text{CAS}}$ or $\overline{\text{RAS}}$	t _{OFF1}	3	15	3	15	3	15	3	15	ns	10,17,20
Output Buffer Turn-off to $\overline{\text{OE}}$	t _{OFF2}		6		8		8		8	ns	17,26
Write Command Setup Time	t _{WCS}	0		0		0		0		ns	11,15,18
Write Command Hold Time	t _{WCH}	5		5		5		5		ns	15,25
Write Command Hold Time(Reference to $\overline{\text{RAS}}$)	t _{WCR}	22		26		30		34		ns	15
Write Command Pulse Width	t _{WP}	5		5		5		5		ns	15
Write Command to $\overline{\text{RAS}}$ Lead Time	t _{RWL}	7		8		9		10		ns	15
Write Command to $\overline{\text{CAS}}$ Lead Time	t _{CWL}	5		6		7		8		ns	15,19
Data-in Setup Time	t _{DS}	0		0		0		0		ns	12,20
Data-in Hold Time	t _{DH}	5		5		5		5		ns	12,20
Data-in Hold Time (Reference to $\overline{\text{RAS}}$)	t _{DHR}	22		26		30		34		ns	
$\overline{\text{RAS}}$ to $\overline{\text{WE}}$ Delay Time	t _{RWD}	34		46		51		56		ns	11
Column Address to $\overline{\text{WE}}$ Delay Time	t _{AWD}	21		31		34		36		ns	11
$\overline{\text{CAS}}$ to $\overline{\text{WE}}$ Delay Time	t _{CWD}	17		25		26		27		ns	11,18
Transition Time (rise or fall)	t _T	1.5	50	1.5	50	2.5	50	2.5	50	ns	2,3
Refresh Period (256 cycles)	t _{REF}		4		4		4		4	ms	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ Precharge Time	t _{RPC}	10		10		10		10		ns	
$\overline{\text{CAS}}$ Setup Time(CBR REFRESH)	t _{CSR}	5		10		10		10		ns	1,18
$\overline{\text{CAS}}$ Hold Time(CBR REFRESH)	t _{CHR}	7		10		10		10		ns	1,19
$\overline{\text{OE}}$ Hold Time From $\overline{\text{WE}}$ During Read-Mode-Write Cycle	t _{OEH}	4		4		4		5		ns	16
$\overline{\text{OE}}$ Low to $\overline{\text{CAS}}$ High Setup Time	t _{OES}	4		4		4		5		ns	
$\overline{\text{OE}}$ High Hold Time From $\overline{\text{CAS}}$ High	t _{OEHC}	2		2		2		2		ns	
$\overline{\text{OE}}$ Precharge Time	t _{OEP}	2		2		2		2		ns	
$\overline{\text{OE}}$ Setup Prior to $\overline{\text{RAS}}$ During Hidden Refresh Cycle	t _{ORD}	0		0		0		0		ns	
Last $\overline{\text{CAS}}$ Going Low to First $\overline{\text{CAS}}$ Returning High	t _{CLCH}	4		5		5		6		ns	21
Data Output Hold After $\overline{\text{CAS}}$ Returning Low	t _{COH}	3		3		3		3		ns	
Output Disable Delay From $\overline{\text{WE}}$	t _{WHZ}	3	7	3	7	3	7	3	7	ns	
Read Setup Time Reference to $\overline{\text{RAS}}$ in CBR	t _{RSR}	5		5		5		5		ns	
Read Hold Time Reference to $\overline{\text{RAS}}$ in CBR	t _{RHR}	5		5		5		5		ns	

Notes :

1. Enables on-chip refresh and address counters.
2. $V_{IH}(\min)$ and $V_{IL}(\max)$ are reference levels for measuring timing of input signals. Transition times are measured between V_{IH} and V_{IL} .
3. In addition to meet the transition rate specification, all input signals must transit between V_{IH} and V_{IL} in a monotonic manner.
4. Assume that $t_{RCD} < t_{RCD}(\max)$. If t_{RCD} is greater than the maximum recommended value shown in this table, t_{RAC} will increase by the amount that t_{RCD} exceeds the value shown.
5. Assume that $t_{RCD} \geq t_{RCD}(\max)$
6. If \overline{CAS} is low at the falling edge of \overline{RAS} , data-out will be maintained from the previous cycle. To initiate a new cycle and clear the data-out buffer, \overline{CAS} and \overline{RAS} must be pulsed high.
7. Operation within the t_{RCD} limit ensures that $t_{RCD}(\max)$ can be met, $t_{RCD}(\max)$ is specified as a reference point only ; if t_{RCD} is greater than the specified $t_{RCD}(\max)$ limit, access time is controlled by t_{CAC} .
8. Operation within the t_{RAD} limit ensures that $t_{RAD}(\max)$ can be met. $t_{RAD}(\max)$ is specified as a reference point only ; if t_{RAD} is greater than the specified $t_{RAD}(\max)$ limit, access time is controlled by t_{AA} .
9. Either t_{RCH} or t_{RRH} must be satisfied for a READ cycle.
10. $t_{OFF1}(\max)$ defines the time at which the output achieves the open circuit condition ; it is not a reference to V_{OH} or V_{OL} .
11. t_{WCS} , t_{RWD} , t_{AWD} and t_{CWD} are restrictive operating parameters in LATE WRITE and READ-MODIFY-WRITE cycle only. If $t_{WCS} \geq t_{WCS}(\min)$, the cycle is an EARLY WRITE cycle and the data output will remain an open circuit throughout the entire cycle. If $t_{RWD} \geq t_{RWD}(\min)$, $t_{AWD} \geq t_{AWD}(\min)$ and $t_{CWD} \geq t_{CWD}(\min)$, the cycle is READ-WRITE and the data output will contain data read from the selected cell. If neither of the above conditions is met, the state of I/O (at access time and until \overline{CAS} and \overline{RAS} or \overline{OE} go back to V_{IH}) is indeterminate. \overline{OE} held high and \overline{WE} taken low after \overline{CAS} goes low result in a LATE WRITE (\overline{OE} -controlled) cycle.
12. Those parameters are referenced to \overline{CAS} leading edge in EARLY WRITE cycles and \overline{WE} leading edge in LATE WRITE or READ-MODIFY- WRITE cycles.
13. During a READ cycle, if \overline{OE} is low then taken HIGH before \overline{CAS} goes high, I/O goes open, if \overline{OE} is tied permanently low, a LATE WRITE or READ-MODIFY-WRITE operation is not possible.
14. An initial pause of 200 μs is required after power-up followed by eight \overline{RAS} refresh cycles (\overline{RAS} only or CBR) before proper device operation is assured. The eight \overline{RAS} cycle wake-ups should be repeated any time the t_{REF} refresh requirement is exceeded.
15. WRITE command is defined as \overline{WE} going low.
16. LATE WRITE and READ-MODIFY-WRITE cycles must have both t_{OFF2} and t_{OEH} met (\overline{OE} high during WRITE cycle) in order to ensure that the output buffers will be open during the WRITE cycles.
17. The I/Os open during READ cycles once t_{OFF1} or t_{OFF2} occur.
18. Referenced to the earlier \overline{CAS} falling edge.
19. Referenced to the latter \overline{CAS} rising edge.
20. Output parameter (I/O) is referenced to corresponding \overline{CAS} input, IO0~7 by \overline{CASL} and IO8~15 by \overline{CASH} .
21. Last falling \overline{CAS} edge to first rising \overline{CAS} edge.
22. Last rising \overline{CAS} edge to next cycle's last rising \overline{CAS} edge.
23. Last rising \overline{CAS} edge to first falling \overline{CAS} edge.
24. Each \overline{CAS} must meet minimum pulse width.
25. Referenced to the latter \overline{CAS} falling edge.
26. All IOs controlled by \overline{OE} , regardless \overline{CASL} and \overline{CASH} .

TRUTH TABLE

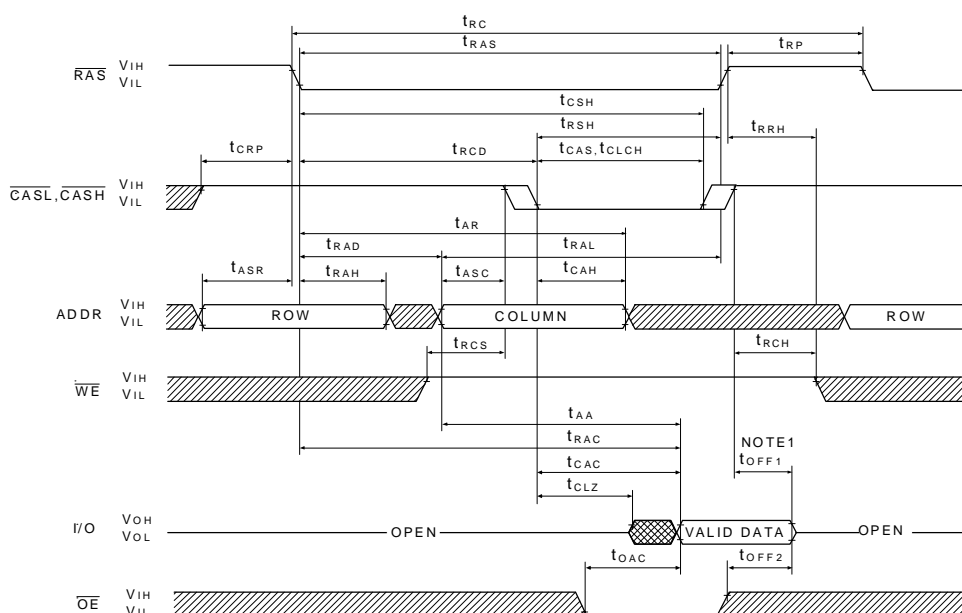
FUNCTION		RAS	CASL	CASH	WE	OE	ADDRESSES		DQs	NOTES
							ROW	COL		
Standby		H	H→X	H→X	X	X	X	X	High-Z	
Read : Word		L	L	L	H	L	ROW	COL	Data-Out	
Read : Lower Byte		L	L	H	H	L	ROW	COL	Lower Byte, Data-Out	
Read : Upper Byte		L	H	L	H	L	ROW	COL	Upper Byte, Data-Out	
Write : Word (Early Write)		L	L	L	L	X	ROW	COL	Data-In	
Write : Lower Byte (Early)		L	L	H	L	X	ROW	COL	Lower Byte, Data-In , Upper Byte, High-Z	
Write : Upper Byte (Early)		L	H	L	L	X	ROW	COL	Lower Byte, High-Z , Upper Byte, Data-In	
Read-Write		L	L	L	H→L	L→H	ROW	COL	Data-Out, Data-In	1, 2
EDO-Page-Mode Read	1st Cycle	L	H→L	H→L	H	L	ROW	COL	Data-Out	2
	2nd Cycle	L	H→L	H→L	H	L		COL	Data-Out	2
	Any Cycle	L	L→H	L→H	H	L			Data-Out	2
EDO-Page-Mode Write	1st Cycle	L	H→L	H→L	L	X	ROW	COL	Data-In	1
	2nd Cycle	L	H→L	H→L	L	X		COL	Data-In	1
EDO-Page-Mode Read-Write	1st Cycle	L	H→L	H→L	H→L	L→H	ROW	COL	Data-Out, Data-In	1, 2
	2nd Cycle	L	H→L	H→L	H→L	L→H		COL	Data-Out, Data-In	1, 2
Hidden Refresh		L→H→L	L	L	H	L	ROW	COL	Data-Out	2
RAS -Only Refresh		L	H	H	X	X	ROW		High-Z	
CBR Refresh		H→L	L	L	H	X	X	X	High-Z	3

*Note : 1. These WRITE cycles may also be BYTE WRITE cycles (either $\overline{\text{CASL}}$ or $\overline{\text{CASH}}$ active).

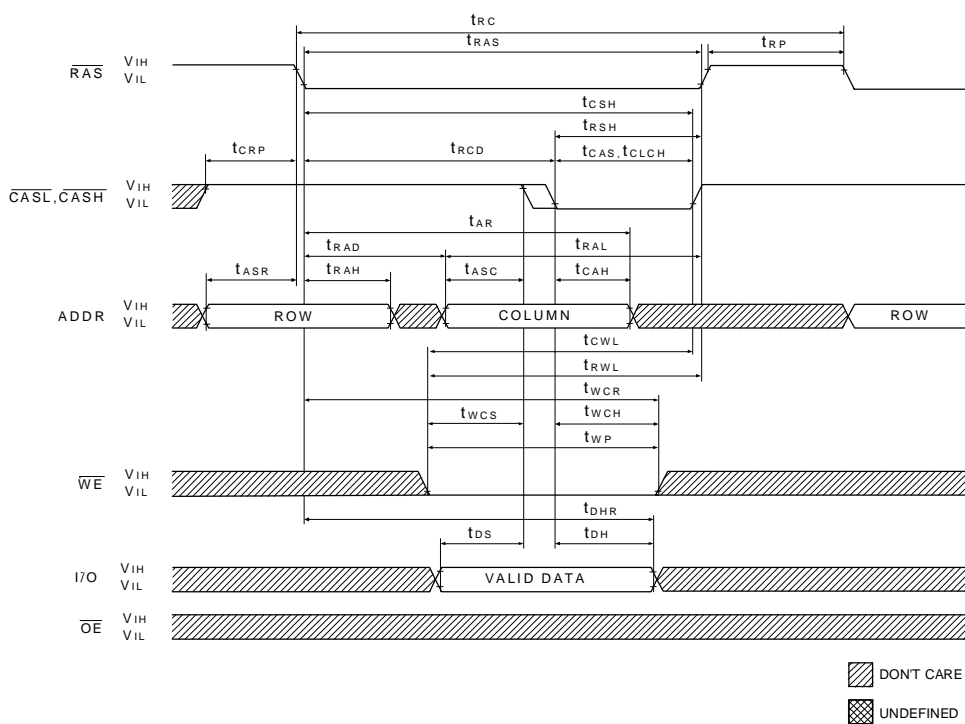
2. These READ cycles may also be BYTE READ cycles (either $\overline{\text{CASL}}$ or $\overline{\text{CASH}}$ active).

3. Only one $\overline{\text{CAS}}$ must be active ($\overline{\text{CASL}}$ or $\overline{\text{CASH}}$).

READ CYCLE

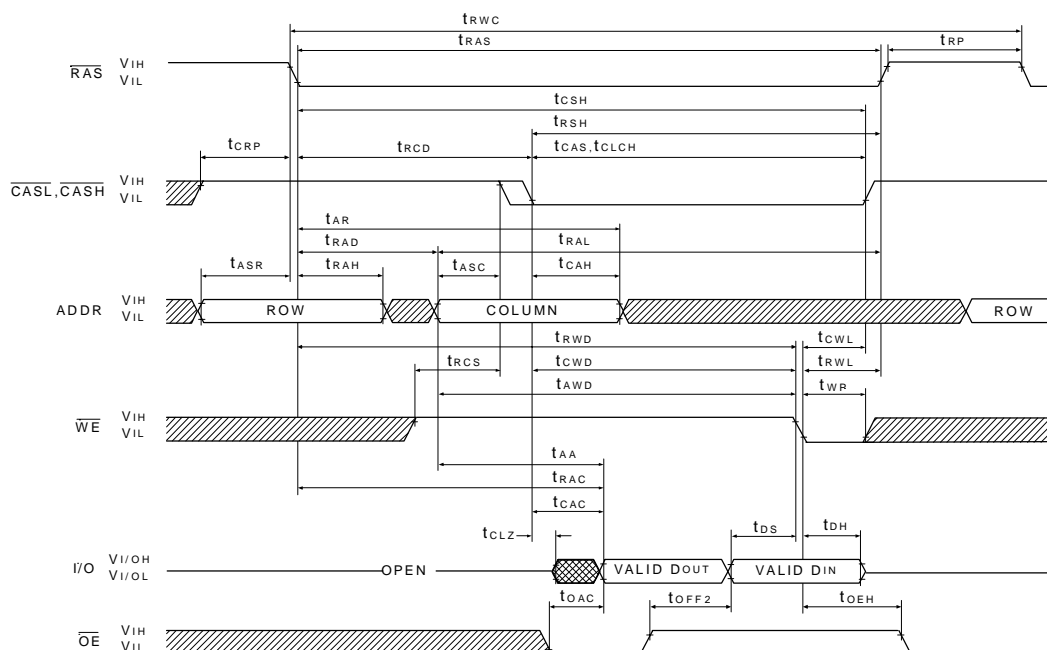


EARLY WRITE CYCLE

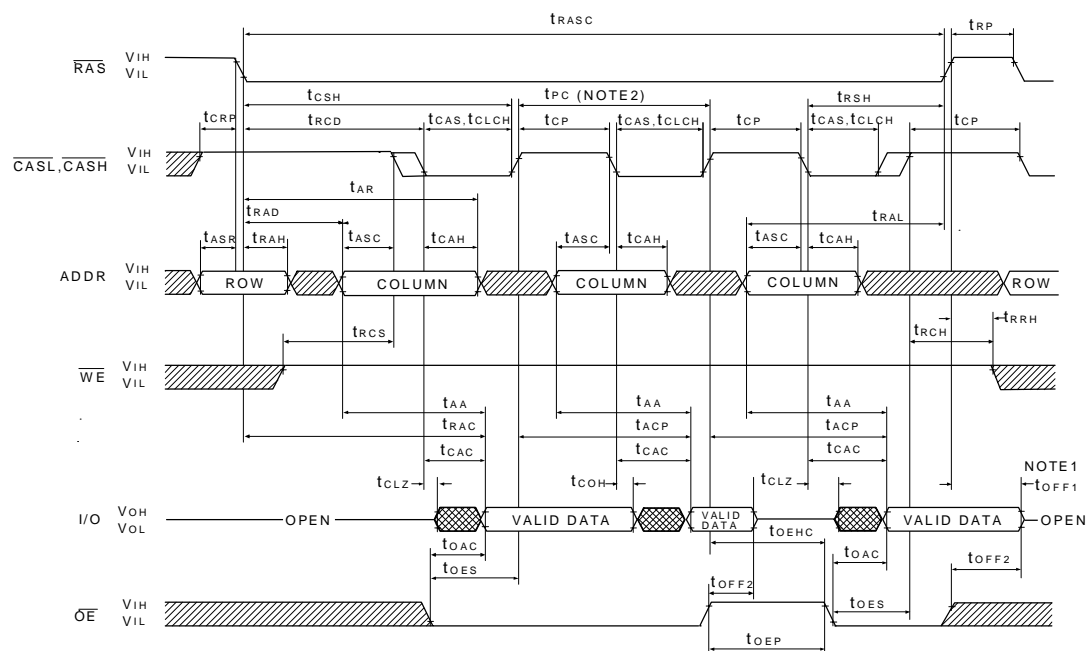


Note: 1. t_{OFF1} is referenced from the rising edge of \overline{RAS} or \overline{CAS} , whichever occurs last.

READ WRITE CYCLE (LATE WRITE and READ-MODIFY-WRITE CYCLES)



EDO-PAGE-MODE READ CYCLE



▨ DONT CARE

▨ UNDEFINED

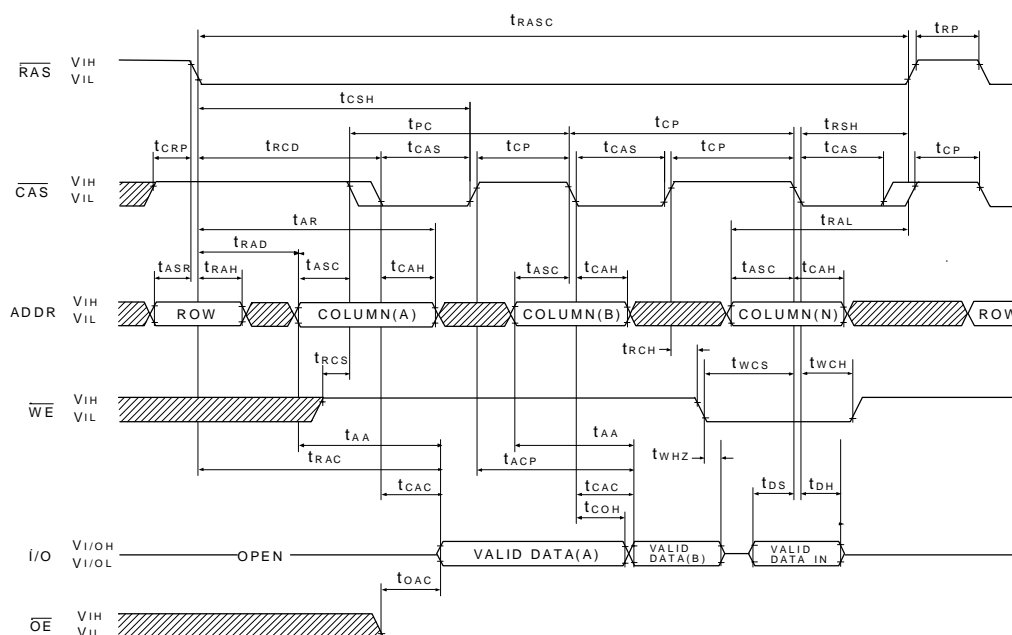
*NOTE : 1. t_{OFF1} is referenced from the rising edge of $\overline{\text{RAS}}$ or $\overline{\text{CAS}}$, whichever occurs last.

2. t_{PC} can be measured from falling edge of $\overline{\text{CAS}}$ to falling edge of $\overline{\text{CAS}}$, or from rising edge of $\overline{\text{CAS}}$ to rising edge of $\overline{\text{CAS}}$. Both measurements must meet the t_{PC} specification.

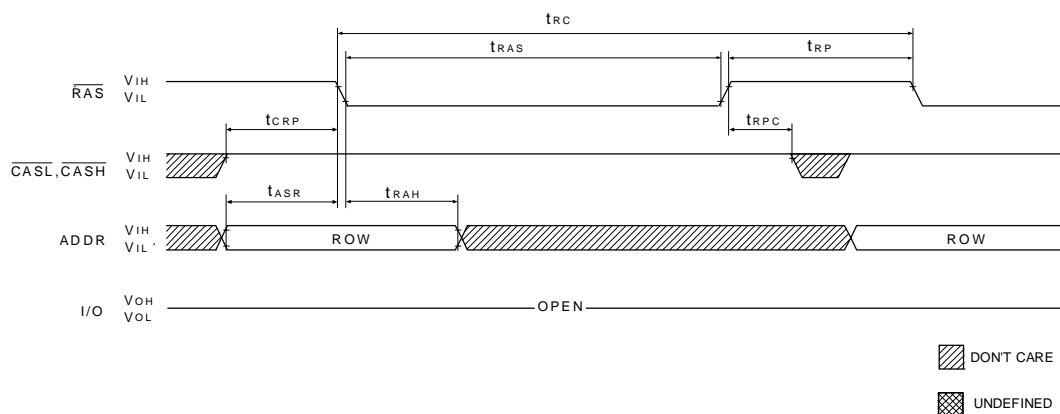
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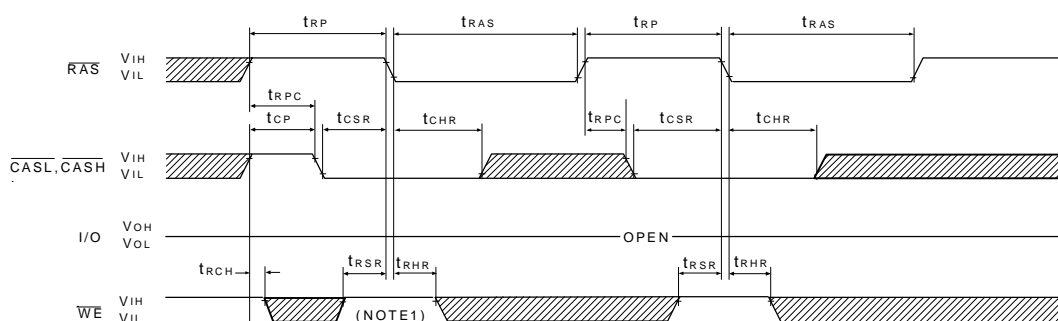
EDO-PAGE-MODE READ-EARLY-WRITE CYCLE (Psuedo READ-MODIFY-WRITE)



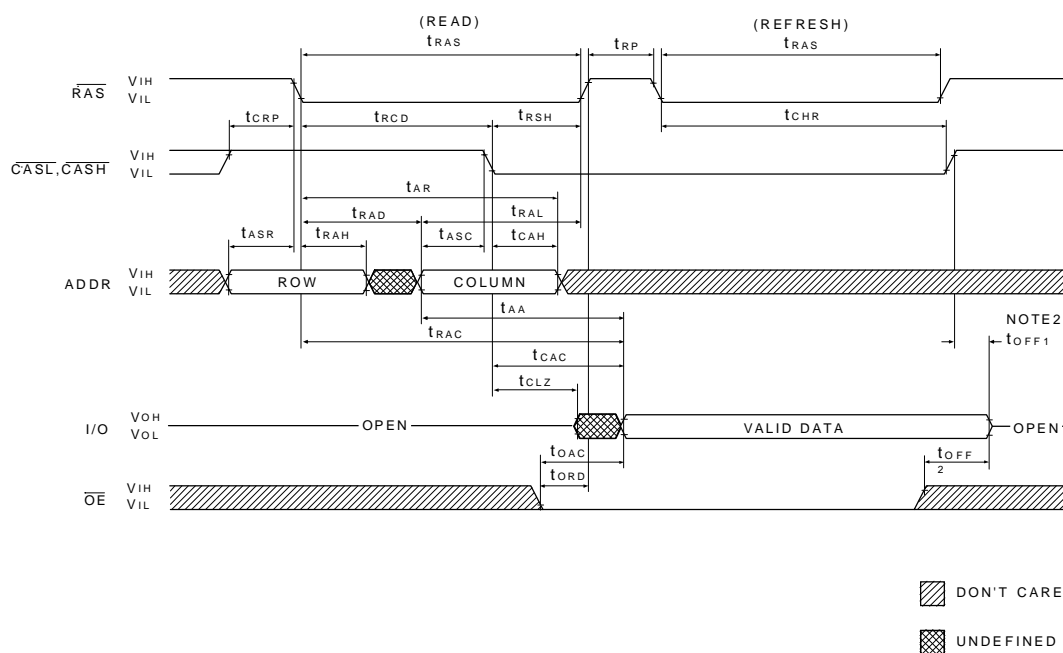
RAS ONLY REFRESH CYCLE
(ADDR = A0~A7 ; $\overline{\text{OE}}$, $\overline{\text{WE}}$ = DON'T CARE)



CBR REFRESH CYCLE
(A0~A7 ; $\overline{\text{OE}}$ = DON'T CARE)



HIDDEN REFRESH CYCLE
 $\overline{\text{WE}} = \text{HIGH} ; \overline{\text{OE}} = \text{LOW}$



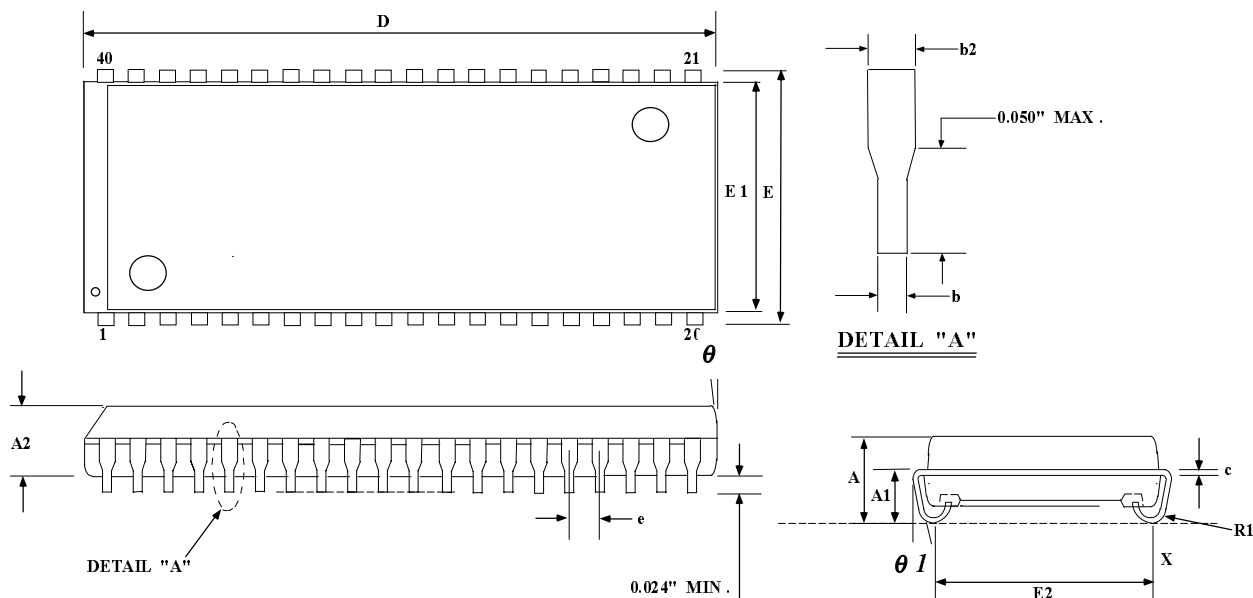
Note : 1. t_{RSR} and t_{RHR} are for system design reference only. The \overline{WE} signal is actually a “don't care” at \overline{RAS} time during a CBR REFRESH. However, \overline{WE} should be held HIGH at \overline{RAS} time during a CBR REFRESH to ensure compatibility with other DRAMs which require \overline{WE} HIGH at \overline{RAS} time during a CBR REFRESH.

2. **toff1** is reference from the rising edge of $\overline{\text{RAS}}$ or $\overline{\text{CAS}}$, whichever occurs last.

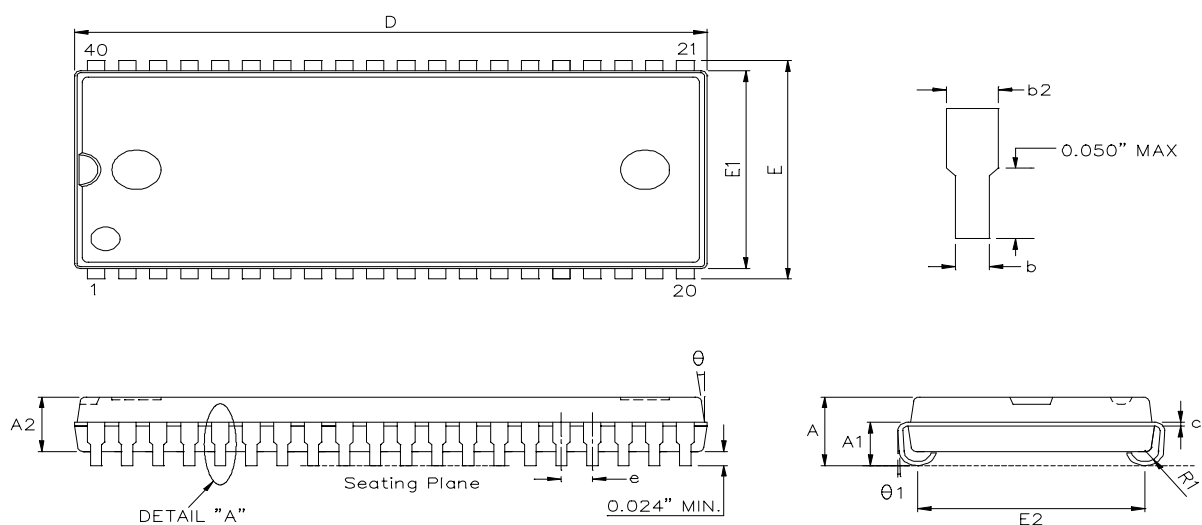
PACKING DIMENSIONS

40-LEAD SOJ(400mil)

SECTION I



SECTION II



Symbol	Dimension in mm			Dimension in inch			Symbol	Dimension in mm			Dimension in inch		
	Min	Norm	Max	Min	Norm	Max		Min	Norm	Max	Min	Norm	Max
A	3.250	3.510	3.760	0.128	0.138	0.148	E	10.920	11.176	11.430	0.430	0.440	0.450
A1	2.080	—	—	0.082	—	—	E1	10.030	10.160	10.290	0.395	0.400	0.405
A2	2.790 REF			0.110 REF			E2	9.40 BSC			0.370 BSC		
b	0.380	0.460	0.560	0.015	0.018	0.022	R1	0.760	0.890	1.020	0.030	0.035	0.040
b2	0.635 REF			0.025 REF			b2	0.635 REF			0.025 REF		
c	0.180	0.250	0.360	0.007	0.010	0.014	$\theta 1$	0°	—	10°	0°	—	10°
e	1.270 BSC			0.050 BSC			e	1.270 BSC			0.050 BSC		
D	25.91	26.040	26.290	1.02	1.025	1.035	y1	—	—	0.381	—	—	0.015

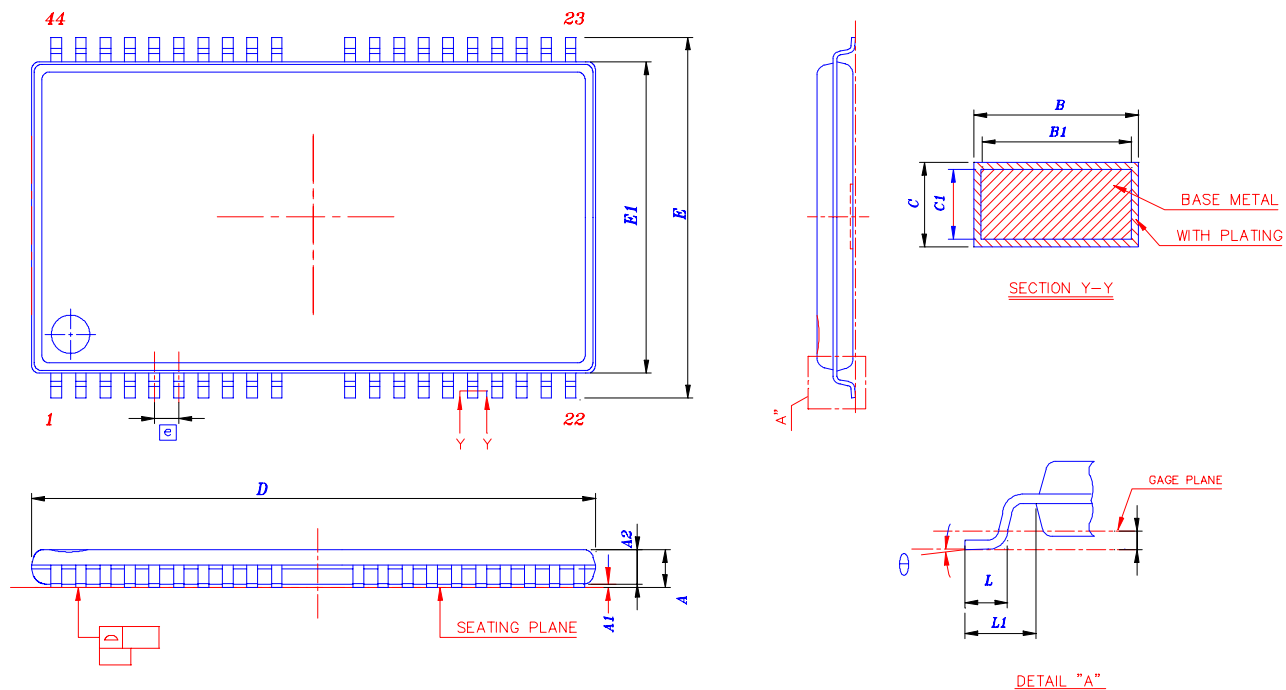
PACKING

DIMENSIONS

40 / 44-LEAD

TSOP(II)

DRAM(400mil)



Symbol	Dimension in mm			Dimension in inch		
	Min	Norm	Max	Min	Norm	Max
A	—	—	1.20	—	—	0.047
A1	0.05	—	0.15	0.002	—	0.006
A2	0.95	1.00	1.05	0.037	0.039	0.042
b	0.30	—	0.45	0.012	—	0.018
b1	0.30	0.35	0.40	0.012	0.014	0.016
c	0.12	—	0.21	0.005	—	0.008
c1	0.10	—	0.16	0.004	—	0.006
D	18.28	18.41	18.54	0.720	0.725	0.730
ZD	0.805 REF			0.0317 REF		
E	11.56	11.76	11.96	0.455	0.463	0.471
E1	10.03	10.16	10.29	0.395	0.400	0.4
L	0.40	0.59	0.69	0.016	0.023	0.027
L1	0.80 REF			0.031 REF		
e	0.80 BSC			0.0315 BSC		
θ	0° ~ 7° REF			0° ~ 7° REF		

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